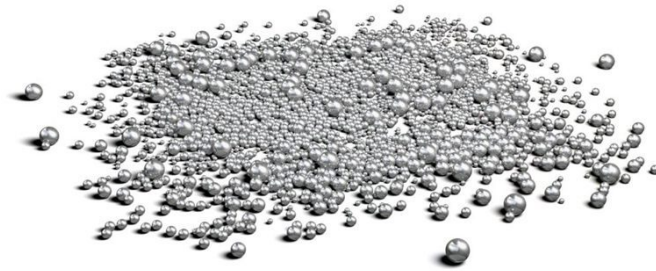
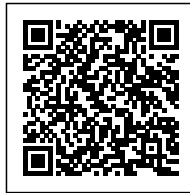


LEAD-FREE SOLDER BALLS SN96.5/AG3/CU0.5 (250.000PCS)



SKU: SBLF



BGA REBALLING BALLS - SN/AG/CU ALLOY

Lead-free solder balls for BGA reballing, available in 9 different diameters.

Alloy composition: **Sn96.5/Ag3/Cu0.5**.

Packaging: **250.000 pieces jar**.

Available sizes (Diameter): 0,25mm – 0,30mm – 0,35mm – 0,40mm – 0,45mm – 0,50mm – 0,55mm – 0,60mm – 0,76mm.

VARIATIONS

| SKU | Description | Diameter |
|---------|-------------|----------|
| 071958C | | 0,25mm |
| 071958D | | 0,30mm |
| 071958E | | 0,35mm |
| 071958F | | 0,40mm |
| 071958G | | 0,45mm |



| SKU | Description | Diameter |
|---------|-------------|----------|
| 071958H | | 0,50mm |
| 071958I | | 0,55mm |
| 071958L | | 0,60mm |
| 071958B | | 0,76mm |